

# Am7942

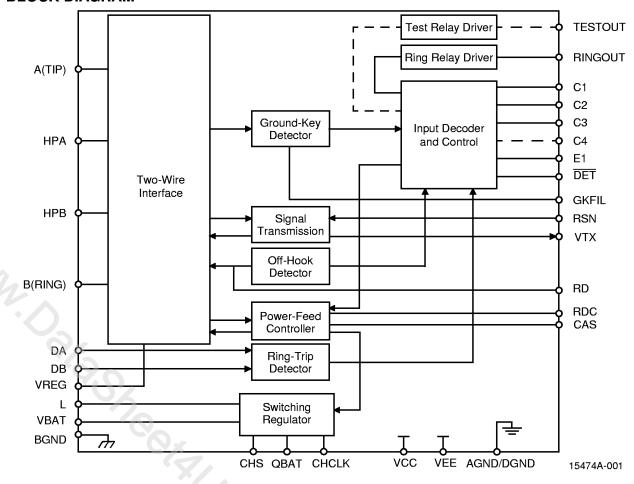
## **Subscriber Line Interface Circuit**

## **DISTINCTIVE CHARACTERISTICS**

- Programmable constant-current feed
- Receive current gain = 200
- Programmable loop-detect threshold
- Low standby power
- Performs polarity reversal
- Ground-key detector
- Pin for external ground-key noise filter capacitor
- Test relay driver option (PLCC only)

- Tip Open state for ground-start lines
- -19 V to -58 V battery operation
- Ideal for PBX and KTS applications
- On-chip switching regulator for low-power dissipation
- Can be used with or without the on-chip switching regulator
- Two-wire impedance set by single external impedance
- On-hook transmission

#### **BLOCK DIAGRAM**

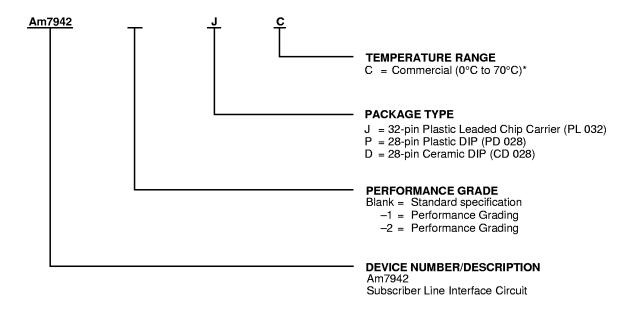


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## **ORDERING INFORMATION**

#### **Standard Products**

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the elements below.



Valid Combinations						
Am7942	-	DC				
	-1	JC				
	-2	PC				

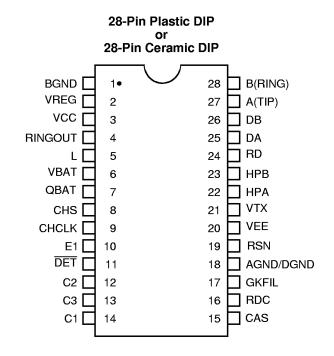
#### **Valid Combinations**

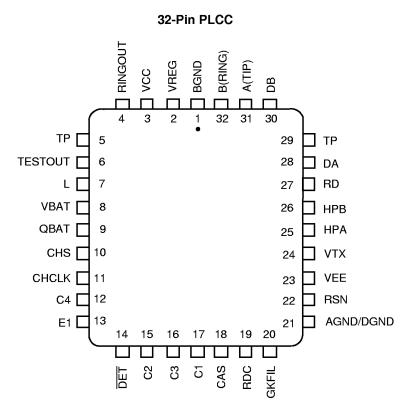
Valid Combinations lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD standard military grade products.

#### Note:

<sup>\*</sup> Functionality of the device from  $0^{\circ}$ C to  $+70^{\circ}$ C is guaranteed by production testing. Performance from  $-40^{\circ}$ C to  $+85^{\circ}$ C is guaranteed by characterization and periodic sampling of production units.

# CONNECTION DIAGRAMS Top View





#### Notes:

- 1. Pin 1 is marked for orientation.
- 2. TP is a thermal conduction pin tied to substrate (QBAT).

# **PIN DESCRIPTIONS**

Pin Names	Туре	Description
AGND/DGND	Gnd	Analog and Digital ground.
A(TIP)	Output	Output of A(TIP) power amplifier.
BGND	Gnd	Battery (power) ground.
B(RING)	Output	Output of B(RING) power amplifier.
C3-C1	Input	Decoder. TTL compatible. C3 is MSB and C1 is LSB.
C4	Input	Test Relay Driver Command. TTL compatible. A logic Low enables the driver. See Note 3.
CAS	Capacitor	Anti-saturation pin for capacitor to filter reference voltage when operating in anti-saturation region.
CHCLK	Input	Chopper Clock. Input to switching regulator (TTL compatible). Freq = 256 kHz (typ). See Note 1.
CHS	Input	Chopper Stabilization. (See Note 1) Connection for external chopper stabilizing components.
DA	Input	Ring-trip negative. Negative input to ring-trip comparator.
DB	Input	Ring-trip positive. Positive input to ring-trip comparator.
DET	Output	Switchhook detector. When enabled, a logic Low indicates the selected detector is tripped. The detector is selected by the logic inputs (C3–C1, E1). The output is open-collector with a built-in 15 k $\Omega$ pull-up resistor.
E1	Input	Ground-Key Enable. E1 = High connects the ground-key detector to DET. E1 = Low connects the off-hook or ring-trip detector to DET.
GKFIL	_	Connection for external ground-key, noise-filter capacitor. See Notes 2 and 3.
HPA	Capacitor	High-Pass Filter Capacitor. A(TIP) side of high-pass filter capacitor.
HPB	Capacitor	High-Pass Filter Capacitor. B(RING) side of high-pass filter capacitor.
L	Output (See Note 1)	Switching Regulator Power Transistor. Connection point for filter inductor and anode of catch diode. Has up to 60 V of pulse waveform on it and must be isolated from sensitive circuits. Keep the diode connections short because of the high currents and high di/dt.
QBAT	Battery	Quiet Battery. (See Note 1). Filtered battery supply for the signal processing circuits
RD	Resistor	Detector resistor. Detector threshold set and filter pin.
RDC	Resistor	DC feed resistor. Connection point for the DC feed current programming network. The other end of the network connects to the receiver summing node (RSN).
RINGOUT	Output	Ring Relay Driver. Open-collector driver with emitter internally connected to BGND.
RSN	Input	Receive Summing Node. The metallic current (AC and DC) between A(TIP) and B(RING) is equal to 500 x the current into this pin. The networks that program receive gain, two-wire impedance, and feed current all connect to this node.
TESTOUT	Output	Test Relay Driver. Open collector driver with emitter internally connected to BGND. See Note 3.
TP	Thermal	Thermal pin. Connection for heat dissipation. Internally connected to substrate (QBAT). Leave as open circuit or connected to QBAT. In both cases, the TP pins can connect to an area of copper on the board to enhance heat dissipation
VBAT	Battery	Battery supply.
VCC	Power	+5 V power supply.
VEE	Power	−5 V power supply.
VREG	Input	Regulated Voltage. (See Note 1.) Provides negative power supply for power amplifiers. Connection point for inductor, filter capacitor, and chopper stabilization.
VTX	Output	Transmit Audio. This output is a unity gain version of the A(TIP) and B(RING) metallic voltage. VTX also sources the two-wire input impedance programming network.

## Notes:

- 1. All pins, except CHCLK, connect to VBAT when using SLIC without a switching regulator. CHCLK is connected to AGND/DGND.
- 2. To prevent noise pickup by the detection circuits when using Ground-Key Detect state (E1 = logical 1), a 3300 pF minimum bypass capacitor is recommended between the GKFIL pin and ground.
- 3. Not available on standard 28-pin DIP package.

## **ABSOLUTE MAXIMUM RATINGS**

Storage temperature	
$V_{EE} \   \text{with respect to AGND/DGND}  + 0.4 \   \text{V to } -7.0 \   \text{V} \\ V_{BAT} \   \text{with respect to AGND/DGND}  + 0.4 \   \text{V to } -70 \   \text{V} \\ \textit{Note: Rise time of $V_{BAT}$ (dv/dt) must be limited to $27$ $V/\mu s$ or less when $Q_{BAT}$ bypass = 0.33 $\mu F$.} \\ BGND \   \text{with respect to AGND/DGND}  .+1.0 \   \text{V to } -3.0 \   \text{V} \\ A(TIP) \   \text{or B(RING)} \   \text{to BGND}: \\ Continuous \qquad70 \   \text{V to } +1.0 \   \text{V} \\ 10 \   \text{ms} \   (\text{f} = 0.1 \   \text{Hz}) \qquad70 \   \text{V to } +5.0 \   \text{V} \\ 10 \   \text{ms} \   (\text{f} = 0.1 \   \text{Hz}) \qquad70 \   \text{V to } +5.0 \   \text{V} \\ 10 \   \text{ms} \   (\text{f} = 0.1 \   \text{Hz}) \qquad70 \   \text{V to } +5.0 \   \text{V} \\ 10 \   \text{ms} \   (\text{f} = 0.1 \   \text{Hz}) \qquad70 \   \text{V to } +1.0 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad70 \   \text{V to } +1.0 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad700 \   \text{V to } +1.5 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +15 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +15 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +15 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +15 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{f} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{hz} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{hz} = 0.1 \   \text{Hz}) \qquad120 \   \text{V to } +10 \   \text{V} \\ 250 \   \text{ns} \   (\text{hz} = 0.1 \   \text{Hz}) \qquad12$	Storage temperature55°C to +150°C
$V_{BAT} \text{ with respect to AGND/DGND} +0.4 \text{ V to } -70 \text{ V} \\ \textit{Note: } \textit{Rise time of } V_{BAT} \textit{ (dv/dt)} \textit{ must be limited to } 27 \textit{ V/}\mu \textit{s or less when } Q_{BAT} \textit{ bypass} = 0.33 \mu \textit{F.} \\ \\ BGND \text{ with respect to AGND/DGND} .+1.0 \text{ V to } -3.0 \text{ V} \\ A(TIP) \text{ or } B(RING) \text{ to } BGND: \\ Continuous70 \text{ V to } +1.0 \text{ V} \\ 10 \text{ ms } (f = 0.1 \text{ Hz})70 \text{ V to } +5.0 \text{ V} \\ 1  \mu \text{s } (f = 0.1 \text{ Hz})90 \text{ V to } +10 \text{ V} \\ 250 \text{ ns } (f = 0.1 \text{ Hz})120 \text{ V to } +15 \text{ V} \\ \\ \text{Current from } A(TIP) \text{ or } B(RING) \pm 150 \text{ mA} \\ \text{Voltage on } RINGOUT BGND \text{ to } 70 \text{ V above } Q_{BAT} \\ \text{Voltage on TESTOUT} BGND \text{ to } 70 \text{ V above } Q_{BAT} \\ \text{Current through relay drivers} 60 \text{ mA} \\ \text{Voltage on ring-trip inputs} \\ \text{(DA and DB)} V_{BAT} \text{ to } 0 \text{ V} \\ \text{Current into ring-trip inputs} \pm 10 \text{ mA} \\ \text{Peak current into regulator} \\ \text{switch (L pin)} 150 \text{ mA} \\ \text{Switcher transient peak off} \\ \text{voltage on L pin} +1.0 \text{ V} \\ \text{C4-C1, E1, CHCLK to } \\ \text{AGND/DGND}0.4 \text{ V to V}_{CC} + 0.4 \text{ V} \\ \text{Maximum power dissipation, T}_{A} \text{ (see note)} 70^{\circ}\text{C} \\ \text{In 28-pin ceramic DIP package} 2.58 \text{ W} \\ \text{In 28-pin plastic DIP package} 1.4 \text{ W} \\ \end{cases}$	$\mbox{V}_{\mbox{\footnotesize CC}}$ with respect to AGND/DGND –0.4 V to +7.0 V
Note: Rise time of $V_{BAT}$ (dv/dt) must be limited to 27 V/μs or less when $Q_{BAT}$ bypass = 0.33 μF.  BGND with respect to AGND/DGND .+1.0 V to -3.0 V A(TIP) or B(RING) to BGND:  Continuous	$V_{\text{EE}}$ with respect to AGND/DGND +0.4 V to -7.0 V
$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	$V_{BAT}$ with respect to AGND/DGND +0.4 V to -70 V
A(TIP) or B(RING) to BGND: Continuous	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	BGND with respect to AGND/DGND .+1.0 V to $-3.0~\text{V}$
$\label{eq:control_problem} \begin{tabular}{lllllllllllllllllllllllllllllllllll$	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
$\label{eq:control_problem} \begin{tabular}{lllllllllllllllllllllllllllllllllll$	Current from A(TIP) or B(RING) $\pm 150$ mA
Current through relay drivers	Voltage on RINGOUT BGND to 70 V above $\mathbf{Q}_{\text{BAT}}$
$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	Voltage on TESTOUT BGND to 70 V above $\mathbf{Q}_{\text{BAT}}$
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	Current through relay drivers 60 mA
Peak current into regulator switch (L pin)	
switch (L pin)	Current into ring-trip inputs ±10 mA
eq:switcher transient peak off voltage on L pin	Peak current into regulator
$\label{eq:continuous} \begin{array}{llllllllllllllllllllllllllllllllllll$	switch (L pin)
$\label{eq:AGND} \begin{array}{cccccccccccccccccccccccccccccccccccc$	
In 28-pin ceramic DIP package 2.58 W In 28-pin plastic DIP package 1.4 W	
In 28-pin plastic DIP package 1.4 W	Maximum power dissipation, $T_A$ (see note) $\dots .70^{\circ}C$
	In 28-pin plastic DIP package 1.4 W

**Note:** Thermal limiting circuitry on chip will shut down the circuit at a junction temperature of about 165°C. The device should never be exposed to this temperature. Operation above 145°C junction temperature may degrade device reliability. See the SLIC Packaging Considerations for more information.

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

## **OPERATING RANGES**

# **Commercial (C) Devices**

Ambient temperature $$
$V_{CC}$
$V_{\text{EE}}$
$V_{BAT}.$
AGND/DGND 0 V
BGND with respect to AGND/DGND100 mV to +100 mV
Load Resistance on VTX to ground $\ldots\ldots$ 10 $k\Omega$ min

The Operating Ranges define those limits between which the functionality of the device is guaranteed.

- \* Functionality of the device from  $0^{\circ}C$  to  $+70^{\circ}C$  is guaranteed by production testing. Performance from  $-40^{\circ}C$  to  $+85^{\circ}C$  is guaranteed by characterization and periodic sampling of production units.
- ◆ Can be used without switching regulator components in this range of battery voltages, provided maximum power dissipation specifications are not exceeded.

# **ELECTRICAL CHARACTERISTICS**

Description	Test Conditions (See Note	1)	Min	Тур	Max	Unit	Note
Analog (V <sub>TX</sub> ) output impedance			3			Ω	4
Analog (V <sub>TX</sub> ) output offset		-1* -2	-35 -35 -30		+35 +35 +30	mV	
		-1* -2	-40 -40 -35		+40 +40 +35	1110	4
Analog (RSN) input impedance	300 Hz to 3.4 kHz			1	20	0	
Longitudinal impedance at A or B					35	Ω	
Overload level	4-wire 2-wire		-2.5		+2.5	Vpk	2
Transmission Performance, 2-Wire In	npedance (See Test Circuit D)						
2-wire return loss	300 Hz to 3400 Hz		26			dB	4, 10
Longitudinal Balance (2-Wire and 4-V	Vire, See Test Circuit C); R <sub>L</sub> =	600 9	Ω			•	
Longitudinal to metallic L-T, L-4	200 Hz to 1 kHz normal polarity 0°C to +70°C normal polarity –40°C to +85°0 reverse polarity	С	52 63 58 54				1, 2 1, 2, 4 1, 2
	1 kHz to 3.4 kHz normal polarity 0°C to +70°C normal polarity -40°C to +85°0 reverse polarity	С	52 58 54 54			dB	1, 2 1, 2, 4 1, 2
Longitudinal signal generation 4-L		-1* -2	40 40 42				
Longitudinal current capability per wire		ıll* ıll		28 18		mArms	
Insertion Loss (2- to 4-Wire and 4- to BAT = $-48$ V, $R_{LDC} = R_{LAC} = 600 \Omega$ ; BA							
Gain accuracy		-1* -2	-0.15 -0.15 -0.10		+0.15 +0.15 +0.10		
		-1* -2	-0.20 -0.20 -0.15		+0.20 +0.20 +0.15	dB	
Variation with frequency		-1* -2	-0.15 -0.15 -0.10		+0.15 +0.15 +0.10		
		-1* -2	-0.20 -0.20 -0.15		+0.20 +0.20 +0.15		 _ 4

Note:

\*P.G. = Performance Grade

# **ELECTRICAL CHARACTERISTICS (CONTINUED)**

Description	Test Conditions (See Note 1)	Min	Тур	Max	Unit	Note
Gain tracking	0°C to +70°C +7 dBm to -55 dBm Reference: -0 dBm	-0.10		+0.10	dB	
	-40°C to +85°C +7 dBm to -55 dBm Reference: -0 dBm	-0.15		+0.15	UD .	4 4 —
Balance Return Signal (4- to 4-Will BAT = -48 V, $R_{LDC}$ = $R_{LAC}$ = 600 $\Omega$	re, See Test Circuit B) ; BAT = –24 V, R <sub>LDC</sub> = 300 Ω, R <sub>LAC</sub> = 6	500 Ω				
Gain accuracy	0 dBm, 1 kHz 0°C to +70°C -1* -2	-0.15 -0.15 -0.10		+0.15 +0.15 +0.10		3 —
	0 dBm, 1 kHz -40°C to +85°C -1* -2	-0.20 -0.20 -0.15		+0.20 +0.20 +0.15		3, 4 3, 4
Variation with frequency	300 Hz to 3400 Hz Relative to 1 kHz 0°C to +70°C	-0.10		+0.10	dB	3
	300 Hz to 3400 Hz Relative to 1 kHz -40°C to +85°C	-0.15		+0.15	ub	3 3 3, 4
Gain tracking	0°C to +70°C +3 dBm to -55 dBm Reference: 0 dBm	-0.10		+0.10		3
	-40°C to +85°C +3 dBm to -55 dBm Reference: 0 dBm	-0.15		-0.15		3, 4
Group delay	f = 1 kHz		5.3		μs	4, 12
Total Harmonic Distortion (2- to 4 BAT = -48 V, $R_{LDC}$ = $R_{LAC}$ = 600 $\Omega$	-Wire and 4- to 2-Wire, See Test Circ	uits A and	В)			
Harmonic distortion	0 dBm		-64	-50	in.	
300 Hz to 3400 Hz	+7 dBm		-55	-40	dB	
Idle Channel Noise BAT = -48 V, R <sub>LDC</sub> = R <sub>LAC</sub> = 600 Ω	; BAT = $-24$ V, $R_{LDC}$ = $300 \Omega$ , $R_{LAC}$ = $6$	500 Ω				
C-message weighted noise	2-wire, 0°C to +70°C 2-wire, -40°C to +85°C		+7	+10 +12	ID 0	4 4
	4-wire, 0°C to +70°C 4-wire, -40°C to +85°C		+7	+10 +12	dBrnC	4 4
Psophometric weighted noise	2-wire, 0°C to +70°C 2-wire, -40°C to +85°C		-83	-80 -78	I.D.	<u> </u>
			-80 -78	dBmp		
Single Frequency Out-of-Band No	ise (See Test Circuit E)					
Metallic	4 kHz to 9 kHz 9 kHz to 1 MHz 256 kHz and harmonics**		-76 -76 -63		dD.co	4 4, 5, 8 4, 5
Longitudinal	1 kHz to 15 kHz Above 15 kHz 256 kHz and harmonics**		-70 -85 -57		dBm	4 4, 5, 8 4, 5

# **ELECTRICAL CHARACTERISTICS (CONTINUED)**

Description	Test Conditions (See Note 1)	Min	Тур	Max	Unit	Note		
Line Characteristics (See Figures 1a, 1b, 1c)								
Short loops, Active state	Battery = $-24$ V, R <sub>LDC</sub> = $300$ $\Omega$ Battery = $-43$ V, R <sub>LDC</sub> = $600$ $\Omega$ Battery = $-48$ V, R <sub>LDC</sub> = $600$ $\Omega$	32.4	35.0	37.6		4, 9 4 —		
Long loops, Active state	Battery = $-24$ V, R <sub>LDC</sub> = $640$ $\Omega$ Battery = $-43$ V, R <sub>LDC</sub> = $1300$ $\Omega$ Battery = $-48$ V, R <sub>LDC</sub> = $1900$ $\Omega$	20.0 23.0 18.0			mA	4, 9 4 —		
OHT state	Battery = $-24$ V, R <sub>LDC</sub> = $600 \Omega$ Battery = $-48$ V, R <sub>LDC</sub> = $600 \Omega$	15.5	17.5	19.5		4, 9 —		
Loop current	Tip Open state, $R_L = 0$ Disconnect state, $R_L = 0$			1.0				
I <sub>L</sub> LIM (ITip and IRing)	Tip and ring shorted to GND		70	105				
Power Dissipation Battery, Norm	al Loop Polarity							
On-hook Open Circuit state	Battery = -24 V, w/o switching reg. Battery = -48 V, with switching reg.		30 35	75 100		9		
On-hook OHT state	Battery = -24 V, w/o switching reg. Battery = -48 V, with switching reg.	100	175 135	225		9		
On-hook Active state	Battery = -24 V, w/o switching reg. Battery = -48 V, with switching reg.		135 180	225 300	mW	9		
Off-hook OHT state $R_L = 50 \ \Omega$	Battery = -24 V, w/o switching reg. Battery = -48 V, with switching reg.		500 400	800 750		9		
Off-hook Active state $R_L = 50 \ \Omega$	Battery = -24 V, w/o switching reg. Battery = -48 V, with switching reg.		800 800	1100 1000		9		
Supply Currents, Battery = -24 V	or –48 V		•			•		
V <sub>CC</sub> on-hook supply current	Open Circuit state OHT state Active state		3.0 6.0 7.5	4.5 10.0 12.0				
V <sub>EE</sub> on-hook supply current	Open Circuit state OHT state Active state		1.0 2.2 2.7	2.3 3.5 6.0	mA	9		
V <sub>BAT</sub> on-hook supply current	Open Circuit state OHT state Active state		0.4 3.0 4.0	1.0 5.0 6.0				

# Note:

<sup>\*\*</sup>Applies only when switching regulator is used.

Power Supply Rejection Ratio (V <sub>RIPPLE</sub> = 50 mVrms)						
V <sub>CC</sub>	50 Hz to 3.4 kHz 3.4 kHz to 50 kHz	25 22	45 35			
V <sub>EE</sub>	50 Hz to 3.4 kHz 3.4 kHz to 50 kHz	20 10	40 25		dB	6
V <sub>BAT</sub>	50 Hz to 3.4 kHz 3.4 kHz to 50 kHz	27 20	45 40			
Effective int. resistance	CAS to GND	85	170	255	kΩ	4

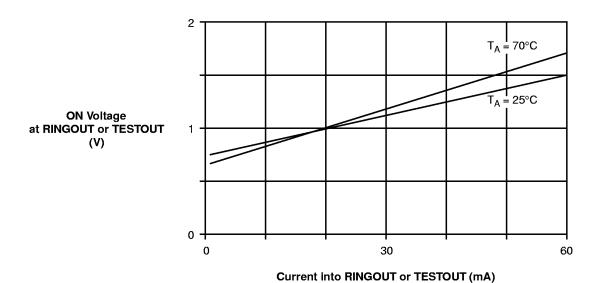
# **ELECTRICAL CHARACTERISTICS (CONTINUED)**

Description	Test Conditions (See Note 1)	Min	Тур	Max	Unit	Note			
Off-Hook Detector			•						
Current threshold	$I_{DET} = 365/R_D$	-20		+20	%				
Ground-Key Detector Thresholds,	Ground-Key Detector Thresholds, Active State								
Ground-key resistance threshold	Battery = -24 V, B(RING) to GND Battery = -48 V, B(RING) to GND	1.0 2.0	2.2 5.0	4.5 10.0	kΩ	9			
Ground-key current threshold	B(RING) to GND Midpoint to GND		9 9		mA	7			
Effective internal resistance	GKFIL to AGND/DGND	18	36	54	kΩ	4			
Ring-Trip Detector Input		•	•						
Bias current		-5	-0.05		μΑ				
Offset voltage	Source resistance = 0 to 2 $M\Omega$	-50	0	+50	mV	11			
Logic Inputs (C4–C1, E0, E1, and C	HCLK)								
Input High voltage		2.0			V				
Input Low voltage				0.8	٧				
Input High current	All inputs except E1	-75		40	μА				
Input High current	Input E1	-75		45	μΑ				
Input Low current		-0.4			mA				
Logic Output (DET)									
Output Low voltage	I <sub>OUT</sub> = 0.8 mA			0.4	<b>V</b>				
Output High voltage	I <sub>OUT</sub> = -0.1 mA	2.4			<b>v</b>				
Relay Driver Outputs (RINGOUT, T	ESTOUT)								
On voltage	25 mA sink			+1.5	V				
Off leakage	V <sub>OH</sub> = +15 V			100	μΑ				

# **RELAY DRIVER SCHEMATICS**



15474A-002

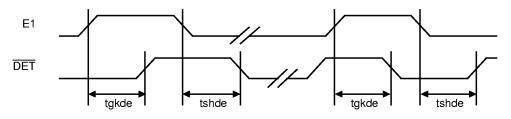


# **SWITCHING CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Temperature Range	Min	Тур	Max	Unit	Note
tgkde	E1 Low to DET High (E0 = 1)	Ground-Key Detect state R <sub>I</sub> open, R <sub>G</sub> connected	0°C to +70°C -40°C to +85°C			3.8 4.0		
	E1 Low to DET Low (E0 = 1)	(See Figure H)	0°C to +70°C -40°C to +85°C			1.1 1.6	. แร	4
tshde	E1 High to DET Low (E0 = 1)	Switchhook Detect state $R_{\rm L} = 600  \Omega$ , $R_{\rm G}$ open	0°C to +70°C -40°C to +85°C			1.2 1.7	μο	<b>T</b>
	E1 High to DET High (E0 = 1)	(See Figure G)	0°C to +70°C -40°C to +85°C			3.8 4.0		

# **SWITCHING WAVEFORMS**

# E1 to DET



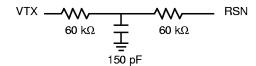
Note:

All delays measured at 1.4 V levels.

15474A-003

#### Notes:

- 1. Unless otherwise noted, test conditions are BAT = -48 V,  $V_{CC}$  = +5 V,  $V_{EE}$  = -5 V,  $R_L$  = 600  $\Omega$ ,  $C_{HP}$  = 0.33  $\mu$ F,  $R_{DC1}$  =  $R_{DC2}$  = 7.14 k $\Omega$ ,  $C_{DC}$  = 0.47  $\mu$ F,  $R_D$  = 35.4 k $\Omega$ ,  $C_{CAS}$  = 0.47  $\mu$ F, no fuse resistors,  $R_T$  = 120 k $\Omega$ , and  $R_{RX}$  = 60 k $\Omega$ . Switching regulator components: L = 1 mH,  $C_{F|L}$  = 0.47  $\mu$ F (see Application Circuit).
- 2. Overload level is defined when THD = 1%.
- Balance return signal is the signal generated at V<sub>TX</sub> by V<sub>RX</sub>. This specification assumes the two-wire AC load impedance matches the programmed impedance.
- 4. Not tested in production. This parameter is guaranteed by characterization or correlation to other tests.
- 5. For frequencies below 12 kHz, these tests are performed with a longitudinal impedance of 90 Ω and metallic impedance of 300 Ω. For frequencies greater than 12 kHz, a longitudinal impedance of 90 Ω and a metallic impedance of 135 Ω is used. These tests are extremely sensitive to circuit board layout. Please refer to application notes for details.
- 6. This parameter is tested at 1 kHz in production. Performance at other frequencies is guaranteed by characterization.
- 7. "Midpoint" is defined as the connection point between two 300 Ω series resistors connected between A(TIP) and B(RING).
- 8. Fundamental and harmonics from 256 kHz switch regulator chopper are not included.
- 9. For –24 V battery, switching regulator is disabled. L, CHS, and VREG pins connected to VBAT pin; CHCLK pin connected to AGND/DGND.
- 10. Assumes the following  $Z_T$  network:



- 11. Tested with 0  $\Omega$  source impedance. 2 M $\Omega$  is specified for system design purposes only.
- 12. Group delay can be considerably reduced by using a Z<sub>T</sub> network such as that shown in Note 10 above. The network reduces the group delay to less than 2 μs. The effect of group delay on linecard performance may be compensated for by using the QSLAC™ or DSLAC™ device.

Table 1. SLIC Decoding

				DET Ou	ıtput					
State	C3 C2 C1		C3 C2 C1		C3 C2 C1		C1	Two-Wire Status	E1 = 0	E1 = 1
О	0	0	0	Open Circuit	Ring trip	Ring trip				
1	0	0	1	Ringing	Ring trip	Ring trip				
2	0	1	0	Active	Loop detector	Ground key				
3	0	1	1	On-Hook TX (OHT)	Loop detector	Ground key				
4	1	0	0	Tip Open	Loop detector	_				
5	1	0	1	Reserved	Loop detector	_				
6	1	1	0	Active Polarity Reversal	Loop detector	Ground key				
7	1	1	1	OHT Polarity Reversal	Loop detector	Ground key				

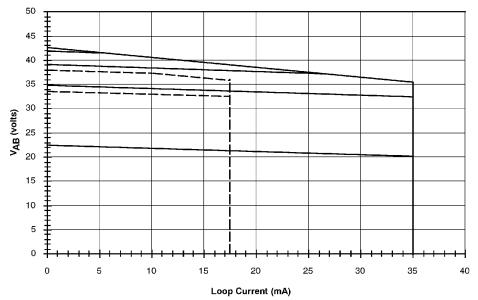
Table 2. User-Programmable Components

$Z_{\rm T} = 200(Z_{\rm 2WIN} - 2R_{\rm F}^*)$	$Z_{T}$ is connected between the VTX and RSN pins. The fuse resistors are $R_{\rm F}$ and $Z_{\rm 2WIN}$ is the desired 2-wire AC input impedance. When computing $Z_{\rm T}$ , the internal current amplifier pole and any external stray capacitance between VTX and RSN must be taken into account.
$Z_{\rm RX} = \frac{Z_{\rm L}}{{\rm G42_{\rm L}}} \bullet \frac{200Z_{\rm T}}{Z_{\rm T} + 200(Z_{\rm L} + 2R_{\rm F})}$	$Z_{RX}$ is connected from $V_{RX}$ to the $R_{SN}.\ Z_T$ is defined above, and $G_{42L}$ is the desired receive gain.
$R_{DC1} + R_{DC2} = \frac{500}{I_{LOOP}}$	$R_{DC1},R_{DC2},$ and $C_{DC}$ form the network connected to the RDC pin. $R_{DC1}$ and $R_{DC2}$ are approximately equal. $I_{LOOP}$ is the desired loop current in the constant-current region.
$C_{\rm DC} = 1.5 \text{ ms} \bullet \frac{R_{\rm DC1} + R_{\rm DC2}}{R_{\rm DC1} R_{\rm DC2}}$	
$R_{\rm D} = \frac{365}{I_{\rm T}},  C_{\rm D} = \frac{0.5 \text{ ms}}{R_{\rm D}}$	$\rm R_D$ and $\rm C_D$ form the network connected from RD to –5 V, and $\rm I_T$ is the threshold current between on hook and off hook.
$C_{CAS} = \frac{1}{3.4 \cdot 10^5 \pi f_c}$	$\mathbf{C}_{CAS}$ is the regulator filter capacitor, and $\mathbf{f}_c$ is the desired filter cut-off frequency.

## Note:

<sup>\*</sup> $R_{FUSE}$  = 20  $\Omega$ –50  $\Omega$ , user selectable.

# DC FEED CHARACTERISTICS



 $R_{DC1} + R_{DC2} = R_{DC} = 14.28 \text{ k}\Omega$ 

Active state OHT state

#### Notes:

1. Constant-current region:

 $I_{\rm L} = \frac{500}{R_{\rm DC}}$ Active state:

 $I_{L} = \frac{250}{R_{DC}}$ OHT state:

2. Anti-saturation turn-on (Active state):

 $V_{AB} = 35.5 \text{ V},$ a. Battery independent:  $(|V_{BAT}| > 46.2 \text{ V})$ 

b. Battery tracking:  $V_{AB} = 1.1 |V_{BAT}| - 15,$  $(|V_{\text{BAT}}| \geq 46.2 \text{ V})$  $(|V_{BAT}| < 46.2 \text{ V})$  $V_{AB} = 0.7 |V_{BAT}| + 3.5,$ 

3. Open circuit voltage:

Active state:  $V_{AB} = 42.6,$  $(|V_{\rm BAT}| > 53~{\rm V})$  $V_{AB} = 0.7 |V_{BAT}| + 5.89,$  $(|V_{\text{BAT}}| \le 53 \text{ V})$ 

OHT state.

 $V_{AB} = 39.1,$   $V_{AB} = 0.7 |V_{BAT}| + 4.7,$  $(|V_{\rm BAT}| > 49.8 \ {\rm V}) \\ (|V_{\rm BAT}| \le 49.8 \ {\rm V})$ 

4. Anti-saturation 1 region:

 $V_{AB} = 46.2 - I_L \left( \frac{R_{DC}}{70.4} \right)$ Active state:

 $V_{AB} = 39.1 - I_L \left( \frac{R_{DC}}{70.4} \right)$ OHT state:

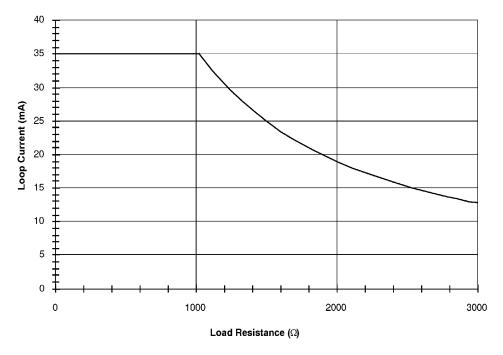
5. Anti-saturation 2 region:

 $V_{AB} = 0.7 |V_{BAT}| + 5.89 - I_L \left(\frac{R_{DC}}{210}\right)$ Active state:

 $V_{AB} = 0.7 |V_{BAT}| + 4.7 - I_L \left(\frac{R_{DC}}{210}\right)$ OHT state:

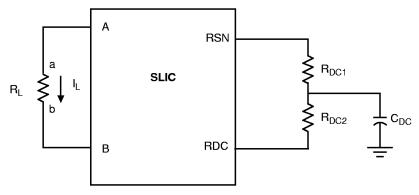
a. V<sub>A</sub>-V<sub>B</sub> (V<sub>AB</sub>) Voltage vs. Loop Current (Typical)

# **DC FEED CHARACTERISTICS (continued)**



$$\begin{split} R_{DC1} + R_{DC2} &= R_{DC} = 14.28 \text{ k}\Omega \\ V_{BAT} &= 47.3 \text{ V} \end{split}$$

b. Loop Current vs. Load Resistance (Typical)



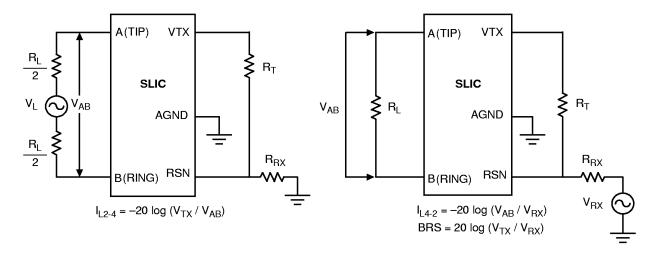
Feed current programmed by  $R_{DC1}$  and  $R_{DC2}$ 

c. Feed Programming

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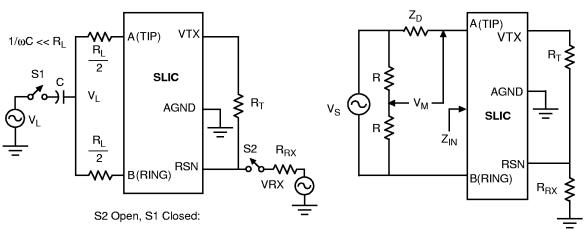
Figure 1. DC Feed Characteristics

## **TEST CIRCUITS**



#### A. Two- to Four-Wire Insertion Loss

B. Four- to Two-Wire Insertion Loss and Balance Return Signal



L-T Long. Bal. = 20 log  $(V_{AB} / V_{L})$ 

L-4 Long. Bal. = 20 log  $(V_{TX} / V_L)$ 

S2 Closed, S1 Open:

4-L Long. Sig. Gen. = 20 log  $(V_L / V_{RX})$ 

# C. Longitudinal Balance

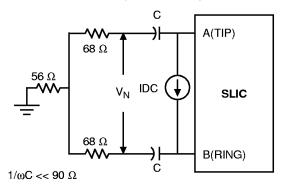
## Note:

 $Z_D$  is the desired impedance (e.g., the characteristic impedance of the line).

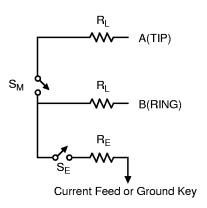
$$R_L = -20 \log (2 V_M / V_S)$$

#### D. Two-Wire Return Loss Test Circuit

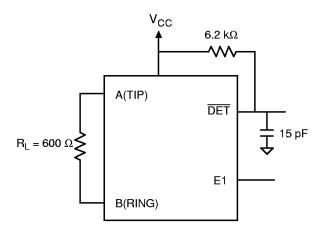
# **TEST CIRCUITS (continued)**



E. Single-Frequency Noise



F. Ground-Key Detection Center Point Test



A(TIP)

B(RING)

 $R_G$ : 2 kΩ at  $V_{BAT} = -48 \text{ V}$ 1 kΩ at  $V_{BAT} = -24 \text{ V}$ 

G. Loop-Detector Switching

H. Ground-Key Switching

## **REVISION SUMMARY**

## **Revision C to Revision D**

- · Minor changes were made to the data sheet style and format to conform to AMD standards.
- Table 1—Some information in the table was revised, including the addition of the Reserved status.

#### Revision D to Revision E

- Minor changes were made to the data sheet style and format to conform to AMD standards.
- In Pin Description table, inserted/changed TP pin description to: "Thermal pin. Connection for heat dissipation. Internally connected to substrate (QBAT). Leave as open circuit or connected to QBAT. In both cases, the TP pins can connect to an area of copper on the board to enhance heat dissipation."

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# **Count Registers**

Each of the three timers has a 16-bit count register. The contents of this register may be read or written by the processor at any time. If the register is written into while the timer is counting, the new value will take effect in the current count cycle.

The count registers should be programmed before attempting to use the timers, since they are not automatically initialized to zero.

#### **Max Count Registers**

Timers 0 and 1 have two MAX COUNT registers, while Timer 2 has a single MAX COUNT register. These contain the number of events the timer will count. In timers 0 and 1, the MAX COUNT register used can alternate between the two MAX COUNT values whenever the current maximum count is reached. A timer resets when the timer count register equals the MAX COUNT value being used. If the timer count register or the MAX COUNT register is changed so that the MAX COUNT is less than the timer count the timer does not immediately reset. Instead, the timer counts up to 0FFFFH, "wraps around" to zero, counts up to the MAX COUNT value, and then resets.

## **Timers and Reset**

Upon RESET, the Timers will perform the following actions:

- All EN (Enable) bits are reset preventing timer counting.
- For Timers 0 and 1, the RIU bits are reset to zero and the ALT bits are set to one. This results in the Timer Out pins going High.
- The contents of the count registers are indeterminate.

#### INTERRUPT CONTROLLER

The 80C186 can receive interrupts from a number of sources, both internal and external. The internal interrupt controller serves to merge these requests on a priority basis, for individual service by the CPU.

Internal interrupt sources (Timers and DMA channels) can be disabled by their own control registers or by mask bits within the interrupt controller. The 80C186 interrupt controller has its own control register that sets the mode of operation for the controller.

The interrupt controller will resolve priority among requests that are pending simultaneously. Nesting is provided so interrupt service routines for lower priority interrupts may themselves be interrupted by higher priority interrupts. A block diagram of the interrupt controller is shown in Figure 19.

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The 80C186 has a special slave mode in which the internal interrupt controller acts as a slave to an external master. The controller is programmed into this mode by setting bit 14 in the peripheral control block relocation register (see Slave Mode section).

## **MASTER MODE OPERATION**

# Interrupt Controller External Interface

Five pins are provided for external interrupt sources. One of these pins is NMI, the non-maskable interrupt. NMI is generally used for unusual events such as power-fail interrupts. The other four pins may be configured in any of the following ways:

- As four interrupt lines with internally generated interrupt vectors.
- As an interrupt line and interrupt acknowledge line pair (cascade mode) with externally generated interrupt vectors plus two interrupt input lines with internally generated vectors.
- As two pairs of interrupt/interrupt acknowledge lines (cascade mode) with externally generated interrupt vectors.

External sources in the cascade mode use externally generated interrupt vectors. When an interrupt is acknowledged, two INTA cycles are initiated and the vector is read into the 80C186 on the second cycle. The capability to interface to external 82C59A programmable interrupt controllers is provided when the inputs are configured in cascade mode.

# Interrupt Controller Modes of Operation

The basic modes of operation of the interrupt controller in master mode are similar to the 82C59A. The interrupt controller responds identically to internal interrupts in all three modes; the difference is only in the interpretation of function of the four external interrupt pins. The interrupt controller is set into one of these three modes by programming the correct bits in the INTO and INT1 control registers. The modes of interrupt controller operation are as follows:

#### **Fully Nested Mode**

When in the fully nested mode four pins are used as direct interrupt requests as in Figure 20. The vectors for these four inputs are generated internally. An in-service bit is provided for every interrupt source. If a lower-priority device requests an interrupt while the in-service bit (IS) is set, no interrupt will be generated by the interrupt controller. In addition, if another interrupt request occurs from the same interrupt source while the in-service bit is set, no interrupt will be generated by the interrupt controller. This allows interrupt service routines to operate

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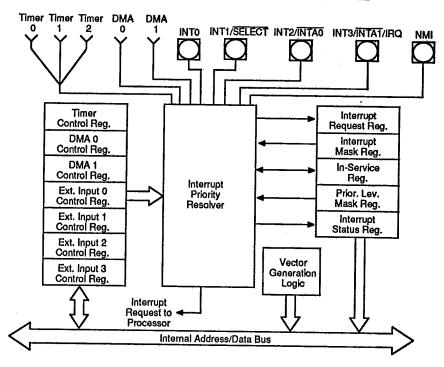


Figure 19. Interrupt Controller Block Diagram

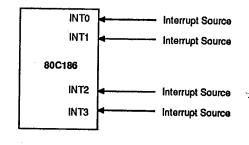
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# **Master Mode Features**

#### **Programmable Priority**

The user can program the interrupt sources into any of eight different priority levels. The programming is done by placing a 3-bit priority level (0–7) in the control register of each interrupt source. (A source with a priority level of 4 has higher priority over all priority levels from 5 to 7. Priority registers containing values lower than 4 have greater priority.) All interrupt sources have preprogrammed default priority levels (see Table 3).

If two requests with the same programmed priority level are pending at once, the priority ordering scheme shown in Table 3 is used. If the serviced interrupt routine reenables interrupts, it allows other interrupt requests to be serviced.



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Figure 20. Fully Nested (Direct) Mode Interrupt Controller Connections

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# **SWITCHING CHARACTERISTICS (continued)**

Ready, Peripheral, and Queue Status Timings

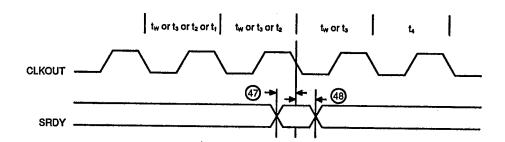
TA = 0°C to +70°C,  $V\infty = 5 \text{ V} \pm 10\%$  except  $V\infty = 5 \text{ V} \pm 5\%$  at f > 12.5 MHz

			Preliminary								T
No	Symbol	Parameter	80C186		80C186-12		80C186-16		80C18620		1-
			Min	Max	Min	Max	Min	Max	Min	Max	Unit
800	C186 Rea	dy and Peripheral Timir	g Requi	rements							
47	tenycu	Synchronous Ready (SRDY) Transition Setup Time <sup>(1)</sup>	15		15		15		10		ns
48	tclsay	SRDY Transition Hold Time(1)	15		15		15		10		ns
49	tarych ,	ARDY Resolution Transition Setup Time <sup>(2)</sup>	15		15		15		10		ns
50	tclarx	ARDY Active Hold	15		15	·	15		10		ns
51	tarychl	ARDY Inactive Holding Time	15		15		15		10		ns
52	<b>L</b> ARYLOL	Asynchronous Ready (ARDY) Setup Time(1)	25		25		25		20		ns
53	t <sub>имсн</sub>	INTx, NMI, TEST/BUSY, TMR IN Setup Time <sup>(2)</sup>	15		15		15		15		ns
54	tinvcl	DRQ0, DRQ1, Setup Time <sup>(2)</sup>	15		15		15		15		ns
80C	186 Peri	pheral and Queue Statu	s Timing	Respor	198	-		<b></b> _			1 110
55	toliny	Timer Output Delay		40		33	I	27		25	ns
56	t <sub>cHOSV</sub>	Queue Status Delay		37		32		30		23	ns

All timings are measured at 1.5 V and 100 pF loading on CLKOUT unless otherwise noted. All output test conditions are with  $C_L = 50-200$  pF (10 MHz) and  $C_L = 50-100$  pF (12.5-20 MHz). For AC tests, input  $V_R = 0.45 \text{ V}$  and  $V_{HI} = 2.4 \text{ V}$  except at  $X_1$  where  $V_{HI} = V_{CC} = 0.5 \text{ V}$ .

Notes: 1. To guarantee proper operation.
2. To guarantee recognition at clock edge.

# Synchronous Ready (SRDY) Waveforms



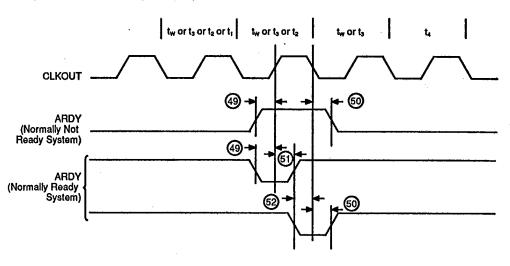
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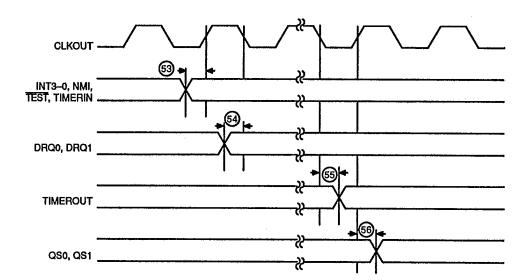
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# Asynchronous Ready (ARDY) Waveforms



## **Peripheral and Queue Status Waveforms**



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